

# PATENT ABSTRACTS OF JAPAN

(11) Publication number : 08-107113

(43) Date of publication of application : 23.04.1996

(51) Int.CI.

H01L 21/324

(21) Application number : 06-266325

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(22) Date of filing : 05.10.1994

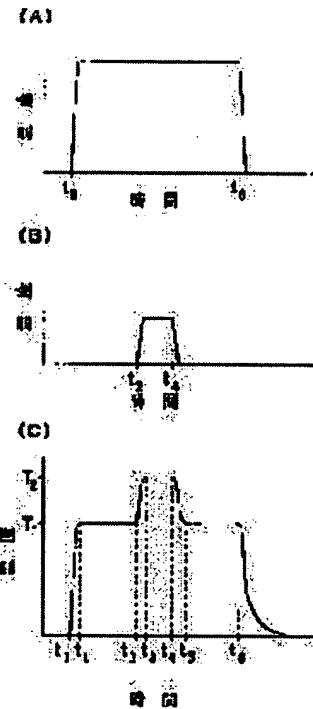
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## (54) HEAT TREATMENT METHOD AND HEAT TREATMENT DEVICE

(57) Abstract:

*PURPOSE: To provide a heat treatment method with which the material to be heat-treated can be stably maintained at the desired temperature while its temperature is rising or lowering.*

*CONSTITUTION: The first and the second heating means are used in the title heat treatment method. (A) The material to be heat-treated is heated up to around the phase transition temperature (T1) of the material which constitutes the material to be heat-treated by operating the first heating means and this temperature state is maintained for the prescribed hours (t1 to t2). (B) Besides, the material to be heat-treated is heated up operating the second heating means in the state wherein the first heating means is in operation, and the material to be heat-treated is maintained at the prescribed temperature (T2) for the prescribed hours (t3 to t4). (C) The operation of the second heating means is stopped while the first heating means is being operated, the temperature of the material to be heat-treated is brought down to around the phase transition temperature (T1) of the material to be heat-treated, and the temperature state is maintained for the prescribed hours (t5 to t6). (D) The operation of the first heating means is stopped, and the material to be heat-treated is cooled*



down.

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**LEGAL STATUS**

*[Date of request for examination]* 19.06.2000

*[Date of sending the examiner's decision of rejection]*

*[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]*

*[Date of final disposal for application]*

*[Patent number]* 3440579

*[Date of registration]* 20.06.2003

*[Number of appeal against examiner's decision of rejection]*

*[Date of requesting appeal against examiner's decision of rejection]*

*[Date of extinction of right]*

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